

FY2024 (April 2023 – March 2024) Financial Announcement

May 10, 2024

Agenda:

- Consolidated Financial Summary
 Hiroshi Kawamoto, Senior Vice President & General Manager, Finance Unit
- Business Environment and Financial Estimates
 Toshiki Kawai, Representative Director, President & CEO

Forward Looking Statements

- Disclaimer regarding forward-looking statements Forward-looking statements with respect to TEL's business plan, prospects and other such information are based on information available at the time of publication. Actual performance and results may differ significantly from the business plan described here due to changes in various external and internal factors, including the economic situation, geopolitical risk, semiconductor market conditions, intensification of sales competition, safety and product quality management, intellectual property-related risks and impacts from COVID-19.
- Processing of numbers
 For the amount listed, because fractions are rounded down, there may be the cases where the total for certain account titles does not correspond to the sum of the respective figures for account titles. Percentages are calculated using full amounts, before rounding.
- Foreign exchange risk
 In principle, export sales of Tokyo Electron's products is denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.



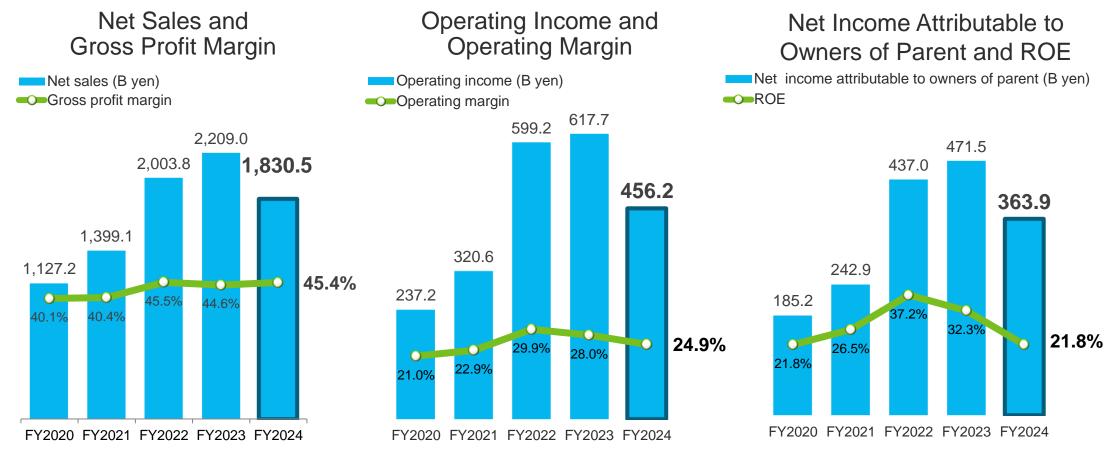
FY2024 Consolidated Financial Summary

May 10, 2024

Hiroshi Kawamoto Senior Vice President & General Manager, Finance Unit



FY2024 (April 2023 – March 2024) Financial Highlights



From the beginning of FY2022, the Company applies "Accounting Standard for Revenue Recognition" (ASBJ Statement No. 29).

Percentages of changes are based on consolidated financial results without the effects of the new standards of the same period of the previous fiscal year.

Although net sales fell 17% YoY, gross profit margin hit a record level through increased sales of high margin products

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Financial Summary

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	FY2023	FY2024	対前期 増減	(Reference) FY2024 estimates announced on February 9, 2024
Net sales	2,209.0	1,830.5	-17.1%	1,830.0
Gross profit Gross profit margin	984.4 44.6%	830.2 45.4%	-15.7% +0.8pts	817.0 44.6%
SG&A expenses	366.6	374.0	+2.0%	372.0
Operating income Operating margin	617.7 28.0%	456.2 24.9%	-26.1% -3.1pts	445.0 24.3%
Income before income taxes	624.8	473.4	-24.2%	450.0
Net income attributable to owners of parent	471.5	363.9	-22.8%	340.0
EPS (Yen)	1,007.82	783.75	-22.2%	732.16
R&D expenses	191.1	202.8	+6.1%	205.0
Capital expenditures	74.4	121.8	+63.7%	124.0
Depreciation and amortization	42.9	52.3	+21.9%	57.0

^{1.} In principle, export sales of Tokyo Electron's products is denominated in yen. Although some sales and expenses are denominated in foreign currencies, the impact of exchange rate fluctuations on profits is negligible, unless extreme fluctuations occur.



^{2.} Profit ratios are calculated using full amounts, before rounding.

^{3.} The Company implemented a 3-for-1 common stock split on April 1, 2023. Net incomes per share are calculated on the assumption that stock split was implemented at the beginning of FY2023.

Financial Summary (Quarterly)

(Billion yen)

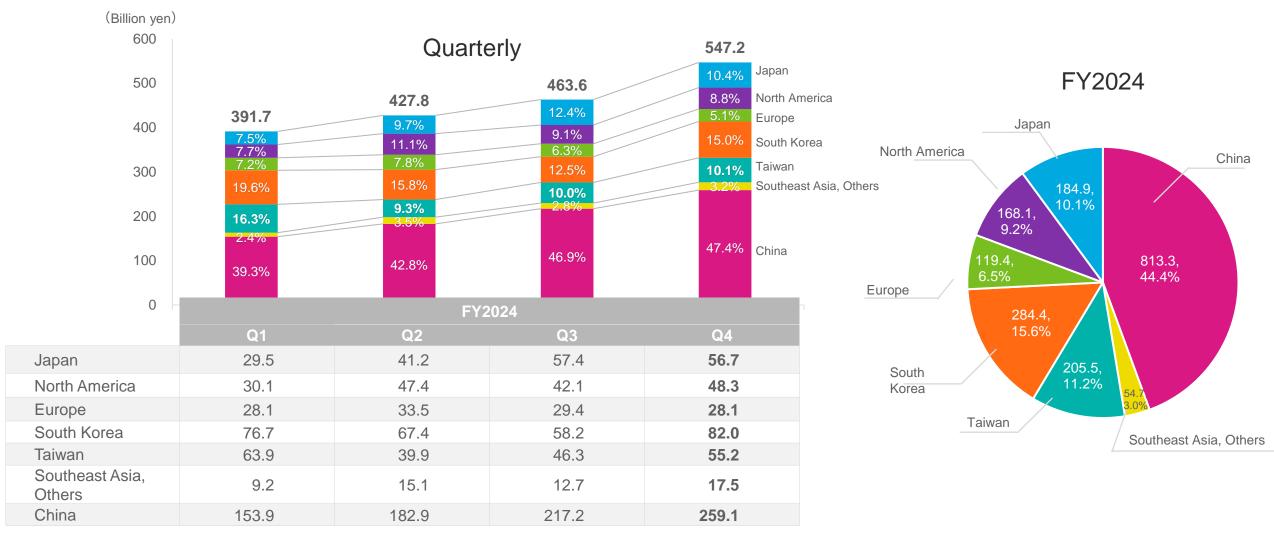
	FY2023 FY2024			QoQ	YoY		
	Q4	Q1	Q2	Q3	Q4	vs. Q3 FY2024	vs. Q4 FY2023
Net sales	558.2	391.7	427.8	463.6	547.2	+18.0%	-2.0%
Gross profit Gross profit margin	251.6 45.1%	162.3 41.4%	189.7 44.3%	222.1 47.9%	256.1 46.8%	+15.3% -1.1pts	+1.8% +1.7pts
SG&A expenses	98.9	79.8	93.5	89.6	110.8	+23.7%	+12.1%
Operating income	152.7	82.4	96.1	132.4	145.2	+9.6%	-4.9%
Operating margin	27.4%	21.0%	22.5%	28.6%	26.5%	-2.1pts	-0.9pts
Income before income taxes	155.6	83.0	98.1	134.4	157.8	+17.4%	+1.4%
Net income attributable to owners of parent	118.6	64.3	73.1	101.5	124.9	+23.1%	+5.3%
R&D expenses	53.7	43.6	51.0	49.7	58.4	+17.3%	+8.6%
Capital expenditures	26.3	39.3	17.6	31.8	32.9	+3.5%	+24.9%
Depreciation and amortization	12.0	10.6	12.5	13.8	15.3	+11.2%	+27.4%

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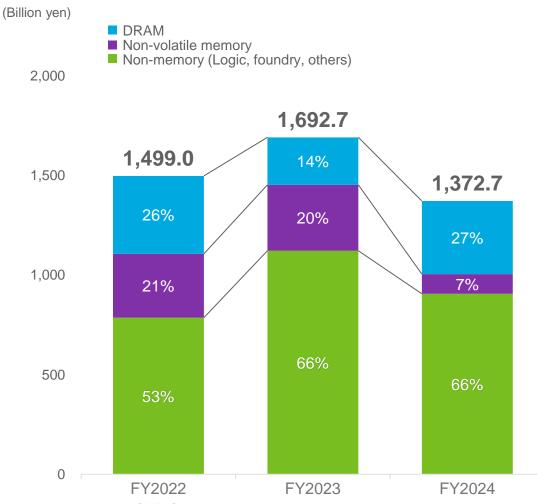


^{2.} Profit ratios are calculated using full amounts, before rounding.

Composition of Net Sales by Region (FY2024 Q1-Q4)



SPE*1 New Equipment Sales by Application



- DRAM: Significant investment by Chinese customers increased both sales and their proportion
- Non-volatile memory: Both sales and proportion fell as capex continued to be restrained due to inventory adjustments by customers
- Non-memory: Although capex for leadingedge was restrained, it was firm for mature generations

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^{*1} SPE: Semiconductor production equipment

^{*2} Percentages on the graph show the composition ratio of new equipment sales. Field Solutions sales are not included.

Field Solutions Sales



 Field Solutions sales in FY2024 were ¥428.5B, down 9.6% YoY

 Both parts and services and used equipment and modification sales declined due to lower customer utilization rate

Balance Sheet (Quarterly)

Assets (Billion Yen) 2,456.4 2,311.5 2,217.4 2,191.7 Cash & cash 2,179.0 472.5 equivalents* 473.1 352.4 362.6 401.0 Notes and accounts receivable (trade, and contract assets) 464.8 368.8 762.9 Inventories 778.0 748.5 652.2 716.5 73.5 Other current assets 72.0 73.8 65.0 150.7 337.3 Tangible assets 317.7 300.4 293.6 259.0 32.3 Intangible assets 30.0 29.8 29.1 28.5 386.2 Investment & other assets 332.1 282.9 304.7 308.6 Q4 Q1 Q2 Q3 Q4 FY2024 FY2023

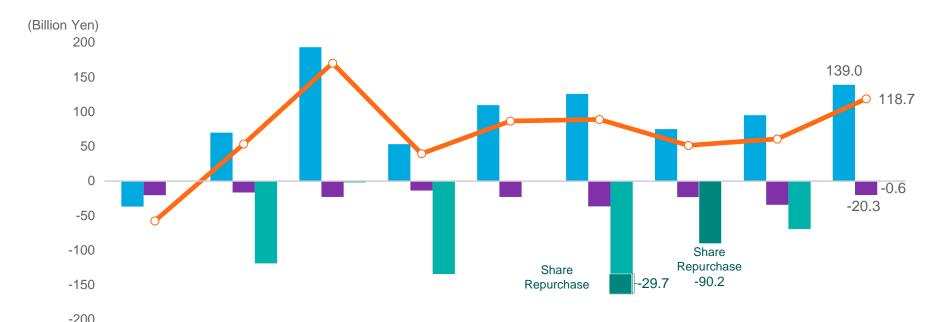
Liabilities & Net Assets



^{*}Cash and cash equivalents: Cash and deposits + Short-term investments, etc. (Securities in B/S).

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Cash Flow (Quarterly)



-200									
	FY2022	FY2023			FY2024				
	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
Cash flow from operating activities	-37.1	69.9	193.4	53.2	109.6	125.7	74.8	95.0	139.0
Cash flow from investing activities*1	-20.7	-16.6	-23.1	-13.8	-23.1	-36.8	-23.4	-34.4	-20.3
Cash flow from financing activities	-0.2	-119.1	-2.1	-134.6	-0.5	-164.1	-90.8	-69.3	-0.6
Free cash flow ^{∗2}	-57.9	53.3	170.2	39.3	86.5	88.8	51.4	60.6	118.7
Cash on hand*3	371.2	314.6	484.6	387.4	473.1	401.0	362.6	352.4	472.5

^{*1} Cash flow from investing activities excludes changes in time deposits and short-term investments.

^{*2} Free cash flow = cash flow from operating activities + cash flow from investing activities (excluding changes in time deposits and short-term investments).

^{*3} Cash on hand includes cash and cash equivalents + time deposits and short-term investments with original maturities of more than three months.



Business Environment and Financial Estimates

May 10, 2024

Toshiki Kawai Representative Director, President & CEO



FY2024 Highlights

- Exceeded initial plan in net sales and profit
 - Nets sales of ¥1,830.5B, operating income of ¥456.2B, net income of ¥363.9B
- R&D investment reached record high of ¥202.8B. New Yamanashi development building established in July 2023
- Made good progress in acquiring PORs*1 through strategic products.
 Released new technologies/products contributing to innovation in semiconductor technology
 - Acquired many PORs for mass production and development in wide range of processes, such as cryogenic etching, conductor etching, super critical drying and bonding for HBM*2, etc.
- Also made progress in non-financial areas such as sustainability
 - All TEL group companies in Japan achieved a rate of 100% renewable energy usage, received SBT *3 certification, etc.
 - Advanced net zero target achievement year by 10 years to CY2040
 - Selected for the SX Brand 2024 (April 2024)
- Completed approximately ¥120.0B share buyback

^{*1} POR (Process of record)

^{*2} HBM (High bandwidth memory)

^{*3} SBT (Science Based Targets)

[:] Certification of the adoption of equipment in customers' semiconductor production processes

[:] A type of DRAM

[:] SBT initiative to certify greenhouse gas emissions reduction targets, conducts assessments of companies' targets. Targets set by companies for the next 5 to 15 years, consistent with the levels mandated by the Paris Agreement.

Business Environment (WFE Market Outlook as of May 2024)

No change in market outlook of a recovery towards CY2025

CY2024: Forecasted to be around \$100B

 Expect leading-edge DRAM investment to recover from H2 on higher demand for DDR5, HBM, etc.

CY2025: Double-digit growth expected

- Continuing growth of AI servers (CAGR 2023-2027: +31%*)
- Recovery in PC/smartphone demand
 - New functions, such as on-device AI, for new applications
 - Replacement of products purchased during COVID-19
 - Corporate IT investment

→ These will drive recoveries forecasted for capex in NAND and advanced logic/foundry following DRAM

*Source: Omdia



Business Opportunities and Focus Areas

	Logic	DRAM	NAND	
Image of device				
Requirements	Low-power / high-speed CPU	High-speed / multi-layer working memory	High-capacity storage	
Technological changes	 GAA Nanosheet Backside PDN*1 	 EUV HKMG*2 in CMOS peripheral circuits HBM packaging 	 Multi-layer/ tier stacking Peripheral bonding Introduction of new materials for memory cells 	
Business opportunities	 Selective etch Deposition with new materials Supercritical drying Bonder/ laser edge trimming 	 Coater/developer for EUV Deposition with new materials Supercritical drying Bonder/debonder 	 HARC etch Wet etch, novel drying technology New low-resistance metal Bonding Wafer warpage suppression technology 	

Growth opportunities are ever-expanding



R&D Investment for Future Growth

- Develop products and technology for the next generation and beyond towards achieving the Mid-term Management Plan
 - Cryogenic etching
 - Conductor etching
 - Single wafer ALD
 - New platform of coater/developer
 - Surface preparation technology for leading-edge lithography
 - Advanced packaging technology
- Enlarge domestic/overseas R&D sites and expand resources
- Strengthen development base
 - Software
 - DX
- Decrease environmental burden, improve safety features, etc.

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Investment for Future Growth (FY2025 to FY2029)

R&D Investment

1.5 trillion yen



Capex

700 billion yen



Recruitment

10,000 people

2,000 people/year



FY2025 Financial Estimates



FY2025 Financial Estimates

(Billion yen)

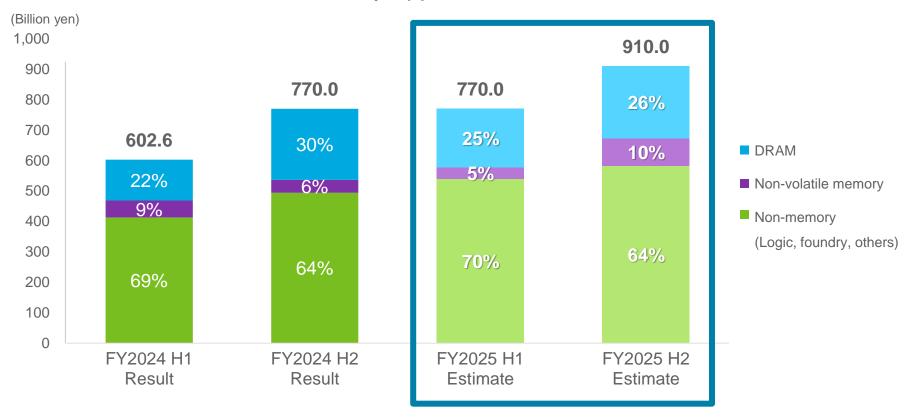
	FY2024	FY2025 (Estimates)					
	(Actual)	H1	H2	Full Year	Full Year YoY		
Net sales	1,830.5	1,000.0	1,200.0	2,200.0	+20.2%		
Gross profit Gross profit margin	830.2 45.4%	454.0 45.4%	568.0 47.3%	1,022.0 46.5%	+23.2% +1.1pts		
SG&A expenses R&D Other than R&D	374.0 202.8 171.1	211.0 118.0 93.0	229.0 132.0 97.0	440.0 250.0 190.0	+17.6% +23.3% +11.0%		
Operating income Operating margin	456.2 24.9%	243.0 24.3%	339.0 28.3%	582.0 26.5%	+27.6% +1.6pts		
Income before income taxes	473.4	244.0	340.0	584.0	+23.4%		
Net income attributable to owners of parent	363.9	185.0	260.0	445.0	+22.3%		
Net income per share (yen)	783.75	399.59	-	961.19	+177.44		

Expecting record-high gross profit and gross profit margin in FY2025. Planning to invest ¥250.0B in R&D to exploit future growth opportunities to the fullest

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FY2025 SPE New Equipment Sales Forecast

Sales by Application



Percentages on the graph show the composition ratio of new equipment sales. Field solutions sales are not included.

Having bottomed out in FY2024 H1, sales are in transition to an upward trend. The proportion of leading-edge investment will/is expected to grow



FY2025 R&D Expenses and Capex Plan

New Development Building

Deposition system, etch system, corporate R&D



Nirasaki-city, Yamanashi Prefecture Established in July 2023

New Development Building

Coater/developer, cleaning system



Koshi-city, Kumamoto Prefecture Completion scheduled for summer 2025

Tohoku Production and Logistics Center

Deposition system



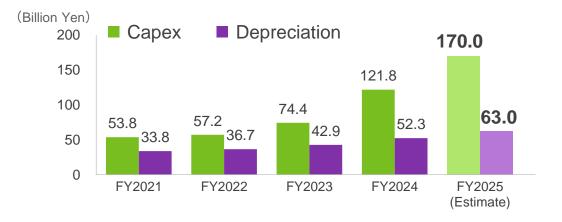
Oshu-city, Iwate Prefecture Completion scheduled for autumn 2025

New Development Building



Kurokawa-gun, Miyagi Prefecture Completion scheduled for spring 2025





Continue aggressive R&D and capital investments for future growth



Acquisition of Treasury Stock

Plan to implement share repurchase of up to 80.0B yen

Type of shares to be acquired : Shares of common stock

Total number of shares to be acquired : Up to 3.5 million shares

(Equivalent to 0.8% of outstanding shares

excluding treasury stock)

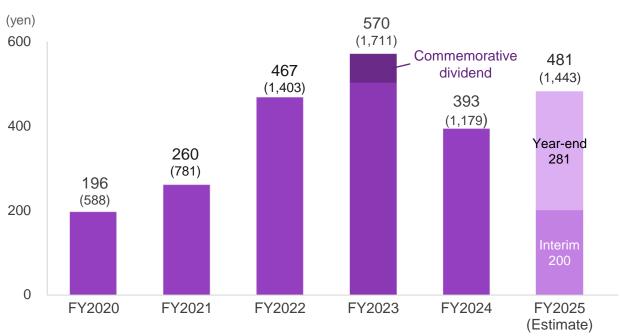
Total cost of acquisition : Up to 80.0 billion yen

Period of acquisition : From May 13, 2024 to July 31, 2024

We will continue to manage our balance sheet flexibly, while considering our ability to generate cash, necessary cash on hand and growth investment capital

FY2025 Dividend Forecast

Dividend per Share



TEL shareholder return policy

Dividend payout ratio: 50%

Annual DPS of not less than 50 yen*

We will review our dividend policy if the company does not generate net income for two consecutive fiscal years

We will flexibly consider share buybacks

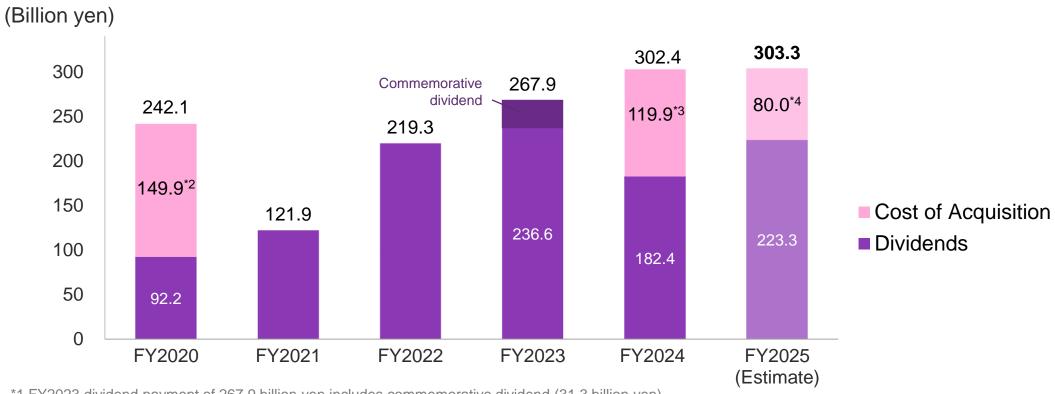
*Due to the stock split on April 1, 2023, the amount has been changed from 150 yen to 50 yen.

- Dividends per share from FY2020 to FY2023 are calculated on the assumption that the stock split was conducted at the beginning of FY2020.
- FY2023 includes the 60th anniversary commemorative dividends.
- Amounts before the stock split are shown in parentheses.

Implemented a 3-for-1 common stock split on April 1, 2023. Full-year dividends are expected to be 481 yen per share

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Total Return Amount



^{*1} FY2023 dividend payment of 267.9 billion yen includes commemorative dividend (31.3 billion yen)

Combined with share buyback, total return amount is expected to be record high

^{*2} https://www.tel.com/news/ir/2020/20200106_001.html

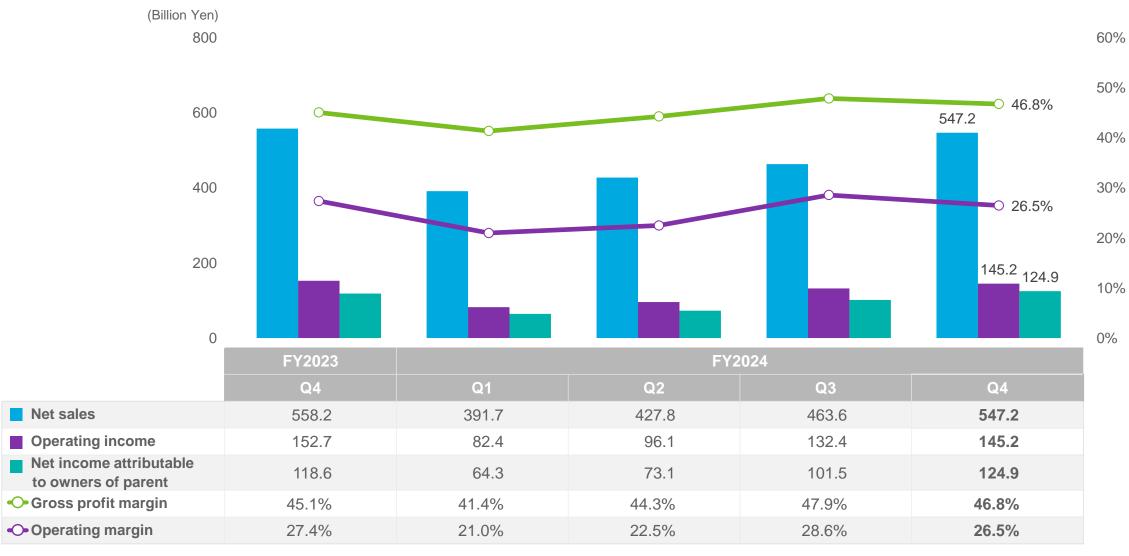
^{*3} https://www.tel.com/news/ir/2023/de4nhu0000000045-att/20231002 001 e.pdf

[&]quot;4 https://www.tel.com/news/ir/2024/bbq72q0000000hu-att/20240510_003_e.pdf

Appendix

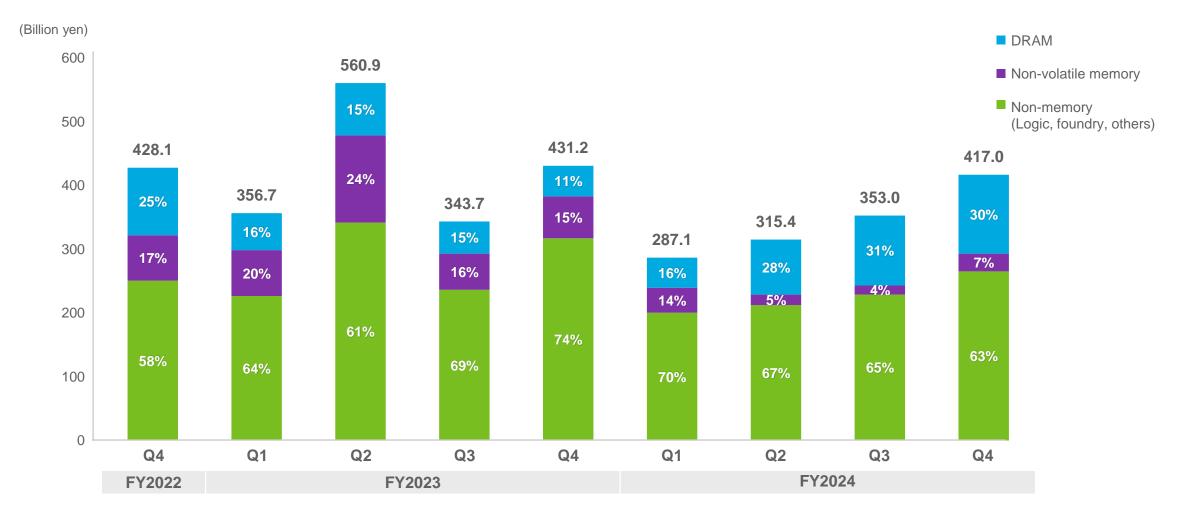


Financial Performance (Quarterly)



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SPE New Equipment Sales by Application (Quarterly)

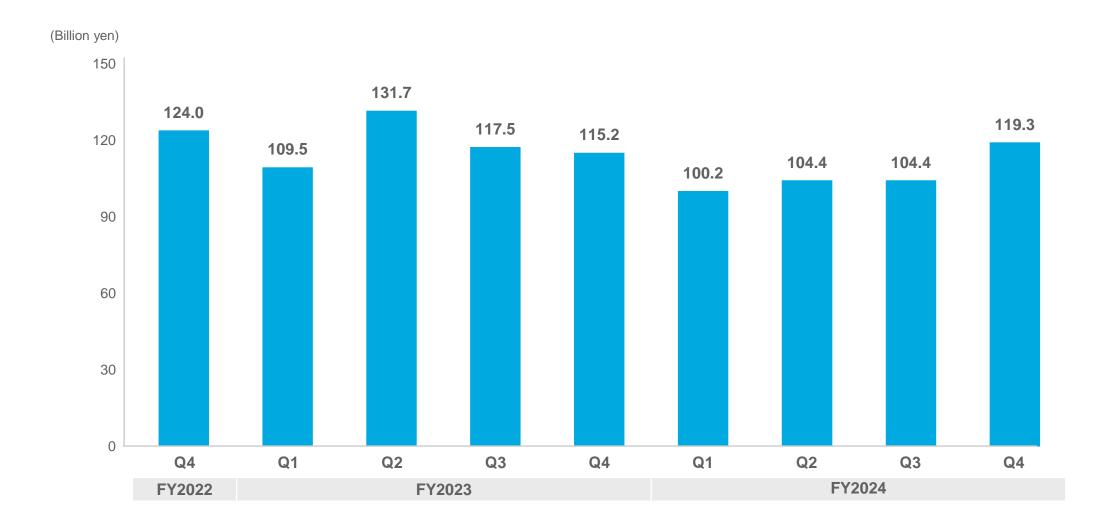


^{*1} SPE: Semiconductor production equipment



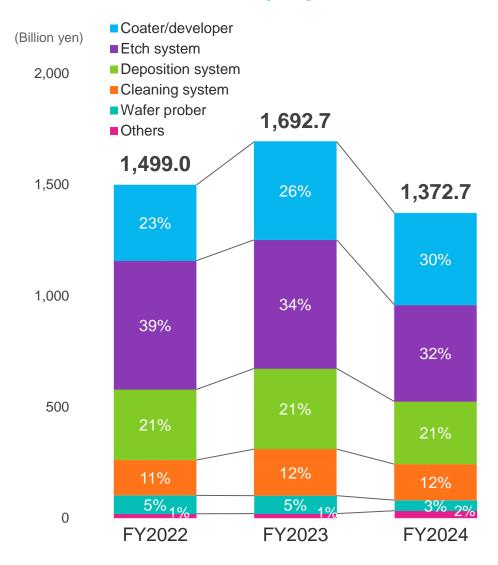
^{*2} Percentages on the graph show the composition ratio of new equipment sales. Field Solutions sales are not included.

Field Solutions Sales (Quarterly)





SPE New Equipment Sales by Product



- New equipment sales in FY2024 were ¥1,372.7, down 18.9% YoY
- Overall sales fell due to capex adjustments.
 However, customers' capex for HBM rose, increasing the proportion of others

Percentages on the graph show the composition ratio of new equipment sales. Field Solutions sales are not included.



Sales by Region



FY2024

121.6

FY2023

54.7

FY2024

200

0



284.4

FY2024

44%

11%

16%

7%

9%

10%

FY2024

16%

11%

FY2023

0%

FY2024

FY2023

200

0

200

0

FY2023

S.E. Asia,

Others

China

Taiwan

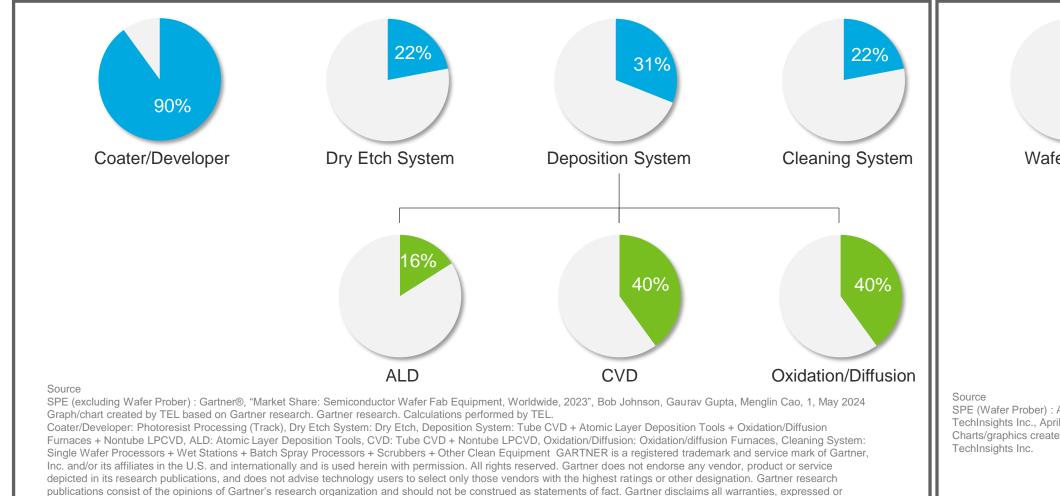
Korea

Europe

Japan

North America

World Market Share of Main Products (CY2023)



34% Wafer Prober SPE (Wafer Prober): Auto Probers, TechInsights Inc., April 2024 Charts/graphics created by Tokyo Electron based on:

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